



**Docket No.: 1293.1967**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

Sung-hee HWANG, et al.

Serial No. 10/670,363

Group Art Unit: 2138

Confirmation No. 5284

Filed: September 26, 2003

Examiner: Phung My Chung

For: METHOD OF AND APPARATUS FOR MANAGING DISC DEFECTS USING  
TEMPORARY DEFECT MANAGEMENT INFORMATION (TDFL) AND TEMPORARY  
DEFECT MANAGEMENT INFORMATION (TDDS), AND DISC HAVING THE TDFL AND  
TDDS

**TERMINAL DISCLAIMER (37 C.F.R. §1.321(C))**

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

**INTEREST AND TITLE OF PERSON MAKING THIS  
TERMINAL DISCLAIMER**

Petitioner, James G. McEwen, represents that I am an attorney of record of the Assignee identified below owning the entire interest in the above-identified application and am authorized to sign on behalf of the Assignee.

**IDENTITY OF ASSIGNEE**

The Assignee is Samsung Electronics Co., Ltd., a corporation organized and existing under the laws of the Republic of Korea, having an office and principal place of business at Suwon-city, Korea.

**RECORDAL OF ASSIGNMENT IN USPTO**

The Assignment of the above-identified application was recorded in the U.S. Patent and Trademark Office on Reel 014547, Frame 0180.

**COMMON OWNERSHIP OF U.S. PATENT APPLICATIONS IN ATTACHMENT A**

Pursuant to Rule 3.73(b), the Assignee is the current owner of the subject application, pursuant to the Assignment identified above. Assignee further confirms that it remains the owner of U.S. Patent Applications set forth in Attachment A.

01 FC:1614

130.00 09

### CERTIFICATION OF TITLE

The evidentiary documents have been reviewed and the undersigned certifies that, to the best of said Assignee's knowledge and belief, title of the above-identified application and the U.S. Patent Applications set forth in Attachment A are in the said Assignee.

### TERMINAL DISCLAIMER

Assignee hereby disclaims the terminal part of the statutory term of any patent, granted on the above-identified application, which would extend beyond the expiration date of any patent granted on the U.S. Patent Applications set forth on Attachment A, and hereby agrees that any patent so granted on the above-identified application shall be enforceable only for and during such period that the legal title to said patent shall be the same as the legal title to any patent granted on the U.S. Patent Applications set forth on Attachment A. This agreement runs with any patent granted on the above-identified application and is to be binding upon the grantee, its successors or assigns.

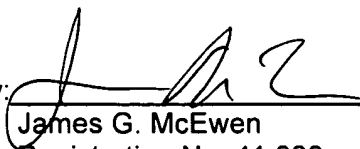
Assignee does not disclaim any terminal part of any patent granted on the above-identified application prior to the expiration date of the full statutory term of any patent granted on the U.S. Patent Applications set forth on Attachment A in the event that one or more of any of any patent granted on the U.S. Patent Applications set forth on Attachment A later expires for failure to pay a maintenance fee, is held unenforceable, is found invalid by a court of competent jurisdiction, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. §1.321, has all claims cancelled by a reexamination certificate, is reissued, or is otherwise terminated prior to the expiration of its statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.

The undersigned hereby declares that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. §1001, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

### FEE

The requisite disclaimer fee under 37 C.F.R. §1.20(d) of \$130.00 is attached hereto.

Date: Oct. 26, 2006

By:   
James G. McEwen  
Registration No: 41,983

**ATTACHMENT A:**  
**LIST OF PATENT APPLICATIONS**

U.S. Patent Application No. 11/045,149

---

U.S. Patent Application No. 11/430,881

---

U.S. Patent Application No. 10/638,481

---

U.S. Patent Application No. 10/663,981

---

U.S. Patent Application No. 11/430,883

---